

Next Generation Memory Market – Global Industry Size, Share, Trends, Opportunity, and Forecast Segmented by Technology (Volatile and Non-Volatile), Application (BFSI, Consumer Electronics, Government, Telecommunications, Information Technology, Other), By Region & Competition, 2019-2029F

<https://marketpublishers.com/r/N71082B2402BEN.html>

Date: October 2024

Pages: 185

Price: US\$ 4,500.00 (Single User License)

ID: N71082B2402BEN

Abstracts

Global Next Generation Memory Market was valued at USD 5.03 Billion in 2023 and is anticipated to project robust growth in the forecast period with a CAGR of 22.89% through 2029. The global Next Generation Memory Market encompasses a diverse range of emerging memory technologies designed to overcome the limitations of traditional memory solutions like DRAM and NAND flash. These next-generation memories promise higher performance, lower power consumption, increased durability, and enhanced scalability, catering to a broad spectrum of applications from consumer electronics to enterprise storage and data centers. One of the key drivers of the Next Generation Memory Market is the exponential growth in data generation and consumption across various sectors. As industries embrace IoT (Internet of Things), AI (Artificial Intelligence), and Big Data analytics, there is an escalating demand for memory solutions capable of handling immense data volumes efficiently. Next-generation memories such as MRAM (Magneto-Resistive RAM), PCM (Phase Change Memory), RRAM (Resistive RAM), and 3D XPoint have emerged as viable alternatives, offering faster read/write speeds, better endurance, and non-volatility compared to conventional technologies.

Key Market Drivers

Increasing Demand for High-Speed, Low-Power Memory Solutions

The global market for next-generation memory is driven by the rising demand for high-speed and low-power memory solutions across various sectors. Traditional memory technologies like DRAM and NAND Flash are reaching their technological limits in terms of speed and power efficiency. Next-generation memory technologies such as Phase Change Memory (PCM), Resistive Random Access Memory (RRAM), and Magnetic Random Access Memory (MRAM) offer significant advantages in terms of speed, energy efficiency, and scalability.

These technologies are particularly suitable for applications requiring fast data access, such as artificial intelligence (AI), machine learning (ML), and big data analytics. For instance, PCM offers faster write speeds and lower power consumption compared to NAND Flash, making it ideal for use in data centers and high-performance computing environments. As industries increasingly adopt these advanced memory solutions to meet their performance and efficiency requirements, the demand for next-generation memory technologies continues to grow.

Proliferation of Internet of Things (IoT) Devices and Edge Computing

The proliferation of IoT devices and the growth of edge computing are significant drivers for the next-generation memory market. IoT devices generate vast amounts of data that need to be processed and analyzed in real-time, often at the edge of the network where latency is critical. Next-generation memory technologies offer the speed and efficiency required to handle these data-intensive applications effectively.

For example, MRAM's non-volatile nature and fast read/write speeds make it suitable for IoT devices that require instant data access and low power consumption. As the number of connected devices continues to rise and edge computing becomes more prevalent, there is an increasing need for memory solutions that can support the high-performance and low-latency requirements of IoT applications. This trend is expected to drive the adoption of next-generation memory technologies in IoT devices, smart sensors, and edge computing platforms.

Growth of Artificial Intelligence and Machine Learning Applications

Artificial intelligence (AI) and machine learning (ML) applications rely heavily on fast data processing and storage capabilities. Next-generation memory technologies offer significant advantages over traditional memory solutions in terms of speed, endurance,

and reliability, making them well-suited for AI and ML workloads.

For instance, RRAM's ability to perform analog computing operations directly in memory can accelerate AI tasks such as neural network training and inference. Similarly, the low latency and high endurance of PCM make it suitable for handling large datasets used in deep learning applications. As AI and ML continue to permeate various industries, the demand for next-generation memory solutions that can support these advanced computing tasks is expected to rise.

Increasing Adoption of Non-Volatile Memory Solutions

Non-volatile memory solutions, which retain data even when the power is turned off, are gaining traction across multiple applications. Next-generation non-volatile memory technologies such as 3D XPoint and FeRAM offer higher density, faster access times, and better endurance compared to traditional NAND Flash memory.

These advantages make them suitable for a wide range of applications, including enterprise storage, automotive electronics, and consumer electronics. For example, 3D XPoint technology, developed jointly by Intel and Micron, promises to deliver a combination of high-speed data access and non-volatility, making it ideal for data-intensive applications in data centers and high-performance computing environments.

As the Demand for faster and more reliable data storage solutions continues to grow, driven by trends such as big data analytics, cloud computing, and the Internet of Things (IoT), the market for next-generation non-volatile memory technologies is expected to expand significantly.

Key Market Challenges

Technological Complexity and Integration Issues

The global next generation memory market faces significant challenges related to technological complexity and integration issues. As the demand for faster, more energy-efficient memory solutions grows, manufacturers are pushed to develop advanced technologies such as Resistive RAM (RRAM), Phase Change Memory (PCM), and Magnetic RAM (MRAM). Each of these technologies offers distinct advantages in terms of speed, power consumption, and durability compared to traditional memory solutions like DRAM and NAND flash. However, integrating these new memory types into existing systems poses several technical hurdles.

One major challenge is compatibility with current architectures and manufacturing processes. Next generation memory technologies often require new design methodologies and materials, which can complicate their integration into established production lines. Manufacturers must invest in research and development to adapt these technologies for mass production while ensuring compatibility with existing infrastructure and standards. This process can be time-consuming and costly, delaying the market entry of new memory products.

The complexity of next generation memory technologies themselves presents integration challenges. For instance, RRAM and PCM involve intricate switching mechanisms and precise control of material properties, requiring sophisticated manufacturing techniques and precise engineering. Achieving consistent performance across different batches and scaling production to meet market demand without compromising quality remains a formidable task.

The variability in performance and reliability of emerging memory technologies adds another layer of complexity. Unlike mature technologies like DRAM, which have well-established reliability metrics, newer memory types may exhibit higher failure rates or lower endurance under certain operating conditions. Addressing these variability issues requires extensive testing and validation processes, which can extend product development cycles and increase costs.

Technological complexity and integration issues pose significant challenges to the global next generation memory market. Overcoming these hurdles requires concerted efforts in research, development, and manufacturing optimization to ensure seamless integration into existing systems and reliable performance under varying conditions.

Cost and Scalability Concerns

Another critical challenge facing the global next generation memory market is cost and scalability concerns associated with manufacturing these advanced memory technologies at scale. While next generation memory types offer compelling advantages in terms of performance and efficiency, their production costs are often higher compared to traditional memory solutions like DRAM and NAND flash.

One of the primary cost drivers is the complexity of materials and manufacturing processes involved in producing next generation memory. For example, RRAM and PCM require specialized materials with precise electrical and thermal properties, which

can be expensive to source and process. Additionally, the fabrication techniques for these memory types often involve advanced lithography and deposition methods, further increasing production costs.

Scalability presents another significant challenge. As demand for faster and denser memory solutions grows, manufacturers must scale production capacity to meet market requirements effectively. However, scaling next generation memory technologies presents unique challenges compared to mature technologies. Issues such as yield rates, manufacturing defects, and production consistency become more pronounced as production volumes increase.

The market economics of next generation memory technologies are influenced by factors such as market acceptance, competition from existing memory solutions, and evolving industry standards. Achieving cost competitiveness with established memory types like DRAM and NAND flash is crucial for widespread adoption of next generation memory technologies across various applications, from consumer electronics to data centers.

The pace of technological advancement and innovation in the semiconductor industry adds uncertainty to cost projections and scalability efforts. Rapid changes in materials science, manufacturing techniques, and design methodologies necessitate continuous investment in research and development to stay competitive and drive down production costs over time.

Addressing cost and scalability concerns is essential for the global next generation memory market to realize its full potential. Manufacturers and industry stakeholders must collaborate on developing cost-effective manufacturing processes, improving yield rates, and enhancing production scalability to drive adoption of next generation memory technologies in diverse applications and market segments.

Key Market Trends

Increased Demand for High-Speed Data Processing and Storage

The global Next Generation Memory market is witnessing a significant trend towards increased demand for high-speed data processing and storage solutions. Traditional memory technologies, such as DRAM and NAND flash, are facing limitations in terms of speed, density, and power efficiency, especially with the exponential growth of data-intensive applications like artificial intelligence (AI), machine learning (ML), and big data

analytics.

Next Generation Memory technologies, such as MRAM (Magnetoresistive Random Access Memory), PCM (Phase-Change Memory), and ReRAM (Resistive Random Access Memory), offer several advantages over traditional options. These technologies provide faster read and write speeds, lower power consumption, and higher density storage capabilities. As organizations seek to handle larger datasets and perform real-time data processing, the demand for these advanced memory solutions continues to rise.

The proliferation of connected devices and the Internet of Things (IoT) further drives the need for reliable and efficient memory solutions that can support diverse applications across various industries. Next Generation Memory addresses these requirements by offering enhanced performance metrics and scalability, thereby supporting the growth of smart devices, autonomous vehicles, and edge computing environments.

Industry leaders are investing heavily in research and development to overcome the technical challenges associated with Next Generation Memory, such as ensuring scalability, reducing production costs, and improving endurance and reliability. As these technologies mature and become more commercially viable, they are expected to play a crucial role in shaping the future of data-centric applications and accelerating innovation in the global semiconductor industry.

Adoption of Non-Volatile Memory in Consumer Electronics and Enterprise Applications

Another prominent trend in the global Next Generation Memory market is the increasing adoption of non-volatile memory solutions in consumer electronics and enterprise applications. Non-volatile memories, such as PCM and ReRAM, offer the advantage of retaining data even when power is turned off, unlike volatile memories like DRAM.

In consumer electronics, there is a growing demand for faster and more energy-efficient storage solutions in smartphones, tablets, and wearable devices. Next Generation Memory technologies provide higher storage capacities and faster access times compared to traditional NAND flash, making them suitable for applications requiring quick data access and processing, such as mobile gaming and multimedia streaming.

Enterprise applications benefit from the reliability and endurance offered by Next Generation Memory. These technologies enable faster data processing and retrieval in servers, data centers, and cloud computing environments, enhancing overall system

performance and reducing latency. As businesses strive to improve operational efficiency and handle vast amounts of data generated from IoT devices and digital transactions, the adoption of advanced memory solutions becomes imperative.

The shift towards edge computing architectures, where data processing occurs closer to the source of data generation, amplifies the need for high-speed and low-latency memory solutions. Next Generation Memory addresses these requirements by supporting real-time analytics, AI inference, and responsive decision-making capabilities at the edge.

As semiconductor manufacturers continue to innovate and introduce new generations of non-volatile memory technologies, the market is poised for substantial growth. The scalability and versatility of Next Generation Memory make it a key enabler for future advancements in consumer electronics, enterprise computing, and emerging technologies like 5G networks and artificial intelligence.

Focus on Energy Efficiency and Sustainability in Memory Solutions

A third significant trend shaping the global Next Generation Memory market is the increasing focus on energy efficiency and sustainability. As the demand for data storage and processing capabilities escalates, so does the energy consumption associated with traditional memory technologies.

Next Generation Memory technologies offer potential energy savings through their inherent design advantages, such as lower power consumption during read and write operations. For instance, MRAM consumes less power than DRAM and retains data without requiring continuous refresh cycles, making it suitable for energy-efficient computing applications.

The semiconductor industry is under pressure to reduce its environmental footprint and minimize resource consumption. Next Generation Memory technologies, with their potential to extend device lifetimes and reduce energy usage in data centers and mobile devices, align with these sustainability goals. Manufacturers are exploring innovative production processes and materials to improve the energy efficiency of memory solutions while adhering to regulatory standards and customer preferences for eco-friendly products.

In addition to energy efficiency, Next Generation Memory technologies offer enhanced durability and reliability, contributing to longer product lifecycles and reducing electronic

waste. This aspect is particularly critical in sectors such as automotive electronics and industrial automation, where robust memory solutions are essential for operating in harsh environments and ensuring continuous operation.

Advancements in 3D stacking and integration techniques enable manufacturers to optimize space utilization and reduce the overall footprint of memory modules, further enhancing energy efficiency and sustainability. These developments pave the way for greener data storage solutions that meet the evolving needs of environmentally conscious consumers and businesses.

The global Next Generation Memory market is driven by the convergence of increased data processing demands, adoption across consumer and enterprise applications, and a growing emphasis on energy efficiency and sustainability. As technology advancements continue to unfold, these trends are expected to shape the competitive landscape and drive innovation in memory solutions, offering compelling opportunities for industry stakeholders and enabling transformative applications in various sectors.

Segmental Insights

Application Insights

Information Technology segment held the largest market share in 2023. The global Next Generation Memory Market in the Information Technology segment is being driven by several key factors that are reshaping the landscape of memory technologies. Next generation memory (NGM) solutions are poised to revolutionize data storage and processing capabilities, addressing the limitations of traditional memory technologies such as DRAM and NAND flash. These advancements are crucial as industries increasingly demand faster, more reliable, and energy-efficient memory solutions to support growing data-intensive applications, including artificial intelligence (AI), big data analytics, IoT (Internet of Things), and 5G networks.

One significant driver is the escalating demand for faster data access speeds and reduced latency in computing systems. Next generation memory technologies, such as Phase Change Memory (PCM), Resistive RAM (RRAM), and MRAM (Magnetoresistive RAM), offer significantly faster read and write speeds compared to traditional NAND flash and DRAM. This capability is particularly vital in AI applications where real-time data processing and inference require rapid access to vast datasets without delays.

Another driver is the need for enhanced energy efficiency and lower power

consumption. As data centers and mobile devices proliferate, the energy efficiency of memory technologies becomes critical. Next generation memories consume less power per operation compared to conventional DRAM and NAND flash, contributing to reduced operational costs and environmental impact. This efficiency is essential in meeting stringent regulatory requirements and sustainability goals while supporting the exponential growth of data traffic globally.

The increasing adoption of IoT devices and connected systems is amplifying the demand for robust, high-performance memory solutions capable of handling diverse workloads. Next generation memories offer greater endurance, reliability, and scalability, making them ideal for edge computing environments where reliability and data integrity are paramount.

The rapid expansion of 5G networks is driving the need for memory solutions that can handle the increased bandwidth and data processing requirements associated with higher network speeds and lower latency. Next generation memories enable faster data caching and retrieval, supporting seamless connectivity and enhanced user experiences across various applications from smart cities to autonomous vehicles.

Technological advancements and innovations in semiconductor manufacturing processes are accelerating the commercialization and adoption of next generation memory technologies. As manufacturers achieve higher yields and production efficiencies, the cost-effectiveness of these advanced memory solutions improves, making them more accessible to a broader range of applications and markets.

The global Next Generation Memory Market in the Information Technology segment is propelled by the imperative for faster speeds, improved energy efficiency, enhanced data handling capabilities, and the proliferation of advanced technologies like AI, IoT, and 5G. These drivers underscore the transformative potential of next generation memory technologies in reshaping the future of computing and data storage, driving innovation across industries and paving the way for more efficient and powerful IT infrastructures globally.

Regional Insights

North America region held the largest market share in 2023. This region's leadership position was underscored by robust investments in research and development, strategic partnerships between industry giants and emerging startups, and a strong consumer demand for innovative memory solutions. The North American market's supremacy in

next-generation memory technologies can be attributed to several key factors. The region boasts a thriving ecosystem of technology hubs, including Silicon Valley in California and various tech corridors across the United States and Canada. North America benefits from a robust infrastructure that supports the commercialization and adoption of next-generation memory solutions. This includes extensive networks of semiconductor manufacturers, research institutions, and venture capital firms that foster a conducive environment for scaling up production and bringing new products to market swiftly.

Another critical factor contributing to North America's dominance is its proactive approach to integrating next-generation memory into various industry verticals. From consumer electronics and automotive applications to enterprise data centers and IoT devices, the region has witnessed widespread adoption of these advanced memory technologies. This adoption is driven by the need for faster data processing speeds, lower power consumption, and enhanced reliability in increasingly data-driven environments.

Government initiatives and policies supporting innovation and technology development have played a pivotal role in North America's leadership in the next-generation memory market. Programs aimed at fostering collaboration between academia, industry, and government bodies have accelerated research breakthroughs and facilitated the transfer of technology from lab to market. In addition to technological prowess and supportive ecosystems, North America's market dominance is bolstered by the presence of leading global players and innovative startups specializing in memory solutions. These companies leverage their expertise in semiconductor design, manufacturing capabilities, and deep understanding of market dynamics to stay at the forefront of technological innovation and maintain a competitive edge.

North America is poised to maintain its leadership in the Global Next Generation Memory Market through continued investments in research and development, strategic partnerships, and advancements in semiconductor manufacturing processes. As technologies such as AI (Artificial Intelligence), edge computing, and 5G networks continue to evolve, the demand for faster, more efficient memory solutions will only intensify, further solidifying North America's pivotal role in shaping the future of memory technologies worldwide.

Key Market Players

Intel Corporation

Toshiba Corporation

Fujitsu Limited

Honeywell International Inc.

Micron Technology Inc.

Sony Group Corporation

Samsung Electronics Co. Ltd

Infineon Technologies AG

IBM Corporation

Report Scope:

In this report, the Global Next Generation Memory Market has been segmented into the following categories, in addition to the industry trends which have also been detailed below:

Next Generation Memory Market, By Technology:

Volatile

Non-Volatile

· Next Generation Memory Market, By Application:

BFSI

Consumer Electronics

Government

Telecommunications

Information Technology

Other

· Next Generation Memory Market, By Region:

North America

United States

Canada

Mexico

Asia-Pacific

China

India

Japan

South Korea

Indonesia

Europe

Germany

United Kingdom

France

Russia

Spain

South America

Brazil

Argentina

Middle East & Africa

Saudi Arabia

South Africa

Egypt

UAE

Israel

Competitive Landscape

Company Profiles: Detailed analysis of the major companies presents in the Global Next Generation Memory Market.

Available Customizations:

Global Next Generation Memory Market report with the given market data, TechSci Research offers customizations according to a company's specific needs. The following customization options are available for the report:

Company Information

Detailed analysis and profiling of additional market players (up to five).

Contents

1. PRODUCT OVERVIEW

- 1.1. Market Definition
- 1.2. Scope of the Market
- 1.3. Markets Covered
- 1.4. Years Considered for Study
- 1.5. Key Market Segmentations

2. RESEARCH METHODOLOGY

- 2.1. Objective of the Study
- 2.2. Baseline Methodology
- 2.3. Key Industry Partners
- 2.4. Major Association and Secondary Sources
- 2.5. Forecasting Methodology
- 2.6. Data Triangulation & Validation
- 2.7. Assumptions and Limitations

3. EXECUTIVE SUMMARY

4. VOICE OF CUSTOMERS

5. GLOBAL NEXT GENERATION MEMORY MARKET OUTLOOK

- 5.1. Market Size & Forecast
 - 5.1.1. By Value
- 5.2. Market Share & Forecast
 - 5.2.1. By Technology (Volatile and Non-Volatile)
 - 5.2.2. By Application (BFSI, Consumer Electronics, Government, Telecommunications, Information Technology, Other)
 - 5.2.3. By Region
- 5.3. By Company (2023)
- 5.4. Market Map

6. NORTH AMERICA NEXT GENERATION MEMORY MARKET OUTLOOK

- 6.1. Market Size & Forecast

- 6.1.1. By Value
- 6.2. Market Share & Forecast
 - 6.2.1. By Technology
 - 6.2.2. By Application
 - 6.2.3. By Country
- 6.3. North America: Country Analysis
 - 6.3.1. United States Next Generation Memory Market Outlook
 - 6.3.1.1. Market Size & Forecast
 - 6.3.1.1.1. By Value
 - 6.3.1.2. Market Share & Forecast
 - 6.3.1.2.1. By Technology
 - 6.3.1.2.2. By Application
 - 6.3.2. Canada Next Generation Memory Market Outlook
 - 6.3.2.1. Market Size & Forecast
 - 6.3.2.1.1. By Value
 - 6.3.2.2. Market Share & Forecast
 - 6.3.2.2.1. By Technology
 - 6.3.2.2.2. By Application
 - 6.3.3. Mexico Next Generation Memory Market Outlook
 - 6.3.3.1. Market Size & Forecast
 - 6.3.3.1.1. By Value
 - 6.3.3.2. Market Share & Forecast
 - 6.3.3.2.1. By Technology
 - 6.3.3.2.2. By Application

7. ASIA-PACIFIC NEXT GENERATION MEMORY MARKET OUTLOOK

- 7.1. Market Size & Forecast
 - 7.1.1. By Value
- 7.2. Market Share & Forecast
 - 7.2.1. By Technology
 - 7.2.2. By Application
 - 7.2.3. By Country
- 7.3. Asia-Pacific: Country Analysis
 - 7.3.1. China Next Generation Memory Market Outlook
 - 7.3.1.1. Market Size & Forecast
 - 7.3.1.1.1. By Value
 - 7.3.1.2. Market Share & Forecast
 - 7.3.1.2.1. By Technology

- 7.3.1.2.2. By Application
- 7.3.2. India Next Generation Memory Market Outlook
 - 7.3.2.1. Market Size & Forecast
 - 7.3.2.1.1. By Value
 - 7.3.2.2. Market Share & Forecast
 - 7.3.2.2.1. By Technology
 - 7.3.2.2.2. By Application
- 7.3.3. Japan Next Generation Memory Market Outlook
 - 7.3.3.1. Market Size & Forecast
 - 7.3.3.1.1. By Value
 - 7.3.3.2. Market Share & Forecast
 - 7.3.3.2.1. By Technology
 - 7.3.3.2.2. By Application
- 7.3.4. South Korea Next Generation Memory Market Outlook
 - 7.3.4.1. Market Size & Forecast
 - 7.3.4.1.1. By Value
 - 7.3.4.2. Market Share & Forecast
 - 7.3.4.2.1. By Technology
 - 7.3.4.2.2. By Application
- 7.3.5. Indonesia Next Generation Memory Market Outlook
 - 7.3.5.1. Market Size & Forecast
 - 7.3.5.1.1. By Value
 - 7.3.5.2. Market Share & Forecast
 - 7.3.5.2.1. By Technology
 - 7.3.5.2.2. By Application

8. EUROPE NEXT GENERATION MEMORY MARKET OUTLOOK

- 8.1. Market Size & Forecast
 - 8.1.1. By Value
- 8.2. Market Share & Forecast
 - 8.2.1. By Technology
 - 8.2.2. By Application
 - 8.2.3. By Country
- 8.3. Europe: Country Analysis
 - 8.3.1. Germany Next Generation Memory Market Outlook
 - 8.3.1.1. Market Size & Forecast
 - 8.3.1.1.1. By Value
 - 8.3.1.2. Market Share & Forecast

- 8.3.1.2.1. By Technology
- 8.3.1.2.2. By Application
- 8.3.2. United Kingdom Next Generation Memory Market Outlook
 - 8.3.2.1. Market Size & Forecast
 - 8.3.2.1.1. By Value
 - 8.3.2.2. Market Share & Forecast
 - 8.3.2.2.1. By Technology
 - 8.3.2.2.2. By Application
- 8.3.3. France Next Generation Memory Market Outlook
 - 8.3.3.1. Market Size & Forecast
 - 8.3.3.1.1. By Value
 - 8.3.3.2. Market Share & Forecast
 - 8.3.3.2.1. By Technology
 - 8.3.3.2.2. By Application
- 8.3.4. Russia Next Generation Memory Market Outlook
 - 8.3.4.1. Market Size & Forecast
 - 8.3.4.1.1. By Value
 - 8.3.4.2. Market Share & Forecast
 - 8.3.4.2.1. By Technology
 - 8.3.4.2.2. By Application
- 8.3.5. Spain Next Generation Memory Market Outlook
 - 8.3.5.1. Market Size & Forecast
 - 8.3.5.1.1. By Value
 - 8.3.5.2. Market Share & Forecast
 - 8.3.5.2.1. By Technology
 - 8.3.5.2.2. By Application

9. SOUTH AMERICA NEXT GENERATION MEMORY MARKET OUTLOOK

- 9.1. Market Size & Forecast
 - 9.1.1. By Value
- 9.2. Market Share & Forecast
 - 9.2.1. By Technology
 - 9.2.2. By Application
 - 9.2.3. By Country
- 9.3. South America: Country Analysis
 - 9.3.1. Brazil Next Generation Memory Market Outlook
 - 9.3.1.1. Market Size & Forecast
 - 9.3.1.1.1. By Value

- 9.3.1.2. Market Share & Forecast
 - 9.3.1.2.1. By Technology
 - 9.3.1.2.2. By Application
- 9.3.2. Argentina Next Generation Memory Market Outlook
 - 9.3.2.1. Market Size & Forecast
 - 9.3.2.1.1. By Value
 - 9.3.2.2. Market Share & Forecast
 - 9.3.2.2.1. By Technology
 - 9.3.2.2.2. By Application

10. MIDDLE EAST & AFRICA NEXT GENERATION MEMORY MARKET OUTLOOK

- 10.1. Market Size & Forecast
 - 10.1.1. By Value
- 10.2. Market Share & Forecast
 - 10.2.1. By Technology
 - 10.2.2. By Application
 - 10.2.3. By Country
- 10.3. Middle East & Africa: Country Analysis
 - 10.3.1. Saudi Arabia Next Generation Memory Market Outlook
 - 10.3.1.1. Market Size & Forecast
 - 10.3.1.1.1. By Value
 - 10.3.1.2. Market Share & Forecast
 - 10.3.1.2.1. By Technology
 - 10.3.1.2.2. By Application
 - 10.3.2. South Africa Next Generation Memory Market Outlook
 - 10.3.2.1. Market Size & Forecast
 - 10.3.2.1.1. By Value
 - 10.3.2.2. Market Share & Forecast
 - 10.3.2.2.1. By Technology
 - 10.3.2.2.2. By Application
 - 10.3.3. UAE Next Generation Memory Market Outlook
 - 10.3.3.1. Market Size & Forecast
 - 10.3.3.1.1. By Value
 - 10.3.3.2. Market Share & Forecast
 - 10.3.3.2.1. By Technology
 - 10.3.3.2.2. By Application
 - 10.3.4. Israel Next Generation Memory Market Outlook
 - 10.3.4.1. Market Size & Forecast

- 10.3.4.1.1. By Value
- 10.3.4.2. Market Share & Forecast
 - 10.3.4.2.1. By Technology
 - 10.3.4.2.2. By Application
- 10.3.5. Egypt Next Generation Memory Market Outlook
 - 10.3.5.1. Market Size & Forecast
 - 10.3.5.1.1. By Value
 - 10.3.5.2. Market Share & Forecast
 - 10.3.5.2.1. By Technology
 - 10.3.5.2.2. By Application

11. MARKET DYNAMICS

- 11.1. Drivers
- 11.2. Challenge

12. MARKET TRENDS & DEVELOPMENTS

13. COMPANY PROFILES

- 13.1. Intel Corporation
 - 13.1.1. Business Overview
 - 13.1.2. Key Revenue and Financials
 - 13.1.3. Recent Developments
 - 13.1.4. Key Personnel
 - 13.1.5. Key Product/Services
- 13.2. Toshiba Corporation
 - 13.2.1. Business Overview
 - 13.2.2. Key Revenue and Financials
 - 13.2.3. Recent Developments
 - 13.2.4. Key Personnel
 - 13.2.5. Key Product/Services
- 13.3. Fujitsu Limited
 - 13.3.1. Business Overview
 - 13.3.2. Key Revenue and Financials
 - 13.3.3. Recent Developments
 - 13.3.4. Key Personnel
 - 13.3.5. Key Product/Services
- 13.4. Honeywell International Inc.

- 13.4.1. Business Overview
- 13.4.2. Key Revenue and Financials
- 13.4.3. Recent Developments
- 13.4.4. Key Personnel
- 13.4.5. Key Product/Services
- 13.5. Micron Technology Inc.
 - 13.5.1. Business Overview
 - 13.5.2. Key Revenue and Financials
 - 13.5.3. Recent Developments
 - 13.5.4. Key Personnel
 - 13.5.5. Key Product/Services
- 13.6. IBM Corporation
 - 13.6.1. Business Overview
 - 13.6.2. Key Revenue and Financials
 - 13.6.3. Recent Developments
 - 13.6.4. Key Personnel
 - 13.6.5. Key Product/Services
- 13.7. Sony Group Corporation
 - 13.7.1. Business Overview
 - 13.7.2. Key Revenue and Financials
 - 13.7.3. Recent Developments
 - 13.7.4. Key Personnel
 - 13.7.5. Key Product/Services
- 13.8. Samsung Electronics Co. Ltd
 - 13.8.1. Business Overview
 - 13.8.2. Key Revenue and Financials
 - 13.8.3. Recent Developments
 - 13.8.4. Key Personnel
 - 13.8.5. Key Product/Services
- 13.9. Infineon Technologies AG
 - 13.9.1. Business Overview
 - 13.9.2. Key Revenue and Financials
 - 13.9.3. Recent Developments
 - 13.9.4. Key Personnel
 - 13.9.5. Key Product/Services

14. STRATEGIC RECOMMENDATIONS

15. ABOUT US & DISCLAIMER

I would like to order

Product name: Next Generation Memory Market – Global Industry Size, Share, Trends, Opportunity, and Forecast Segmented by Technology (Volatile and Non-Volatile), Application (BFSI, Consumer Electronics, Government, Telecommunications, Information Technology, Other), By Region & Competition, 2019-2029F

Product link: <https://marketpublishers.com/r/N71082B2402BEN.html>

Price: US\$ 4,500.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/N71082B2402BEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below
and fax the completed form to +44 20 7900 3970